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June 2013

2N5551 / MMBT5551 NPN General-Purpose Amplifier

Description

This device is designed for general-purpose high-voltage amplifiers and gas discharge display drivers.

2N5551



MMBT5551



1. Base 2. Emitter 3. Collector

Ordering Information(1)

Part Number	Top Mark	Package Packing Method		
2N5551TA	5551	TO-92 3L	Ammo	
2N5551TFR	5551	TO-92 3L	Tape and Reel	
2N5551TF	5551	TO-92 3L	Tape and Reel	
2N5551BU	5551	TO-92 3L	Bulk	
MMBT5551	3S	SOT-23 3L	Tape and Reel	

Note:

1. Suffix "-C" means Center Collector in 2N5551 (1. Emitter 2. Collector 3. Base) Suffix "-Y" means h_{FE} 180~240 in 2N5551 (Test condition: I_C = 10 mA, V_{CE} = 5.0 V)

Absolute Maximum Ratings(2)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^{\circ}$ C unless otherwise noted.

Symbol	Parameter	Value	Units
V _{CEO}	Collector-Emitter Voltage	160	V
V _{CBO}	Collector-Base Voltage	180	V
V _{EBO}	Emitter-Base Voltage	6	V
I _C	Collector current - Continuous	600	mA
T _J , T _{stg} ⁽²⁾	Junction and Storage Temperature	-55 to +150	°C

Notes:

- 2. These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.
- 3. These ratings are based on a maximum junction temperature of 150 $^{\circ}$ C.

These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty cycle operations.

Thermal Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Maximum			Units	
	Parameter		N5551	MMBT5	551	Units
D	Total Device Dissipation		625	350		mW
P _D	Derate above 25°C		5.0	2.8		mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		83.3			°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		200	357		°C/W

Electrical Characteristics(4)

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Charac	cteristics				
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage	$I_C = 1.0 \text{ mA}, I_B = 0$	160		V
V _{(BR)CBO}	Collector-Base Breakdown Voltage	$I_C = 100 \mu\text{A}, I_E = 0$	180		V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$I_E = 10 \mu\text{A}, I_C = 0$	6.0		V
I _{CBO}	Collector Cut-Off Current	V _{CB} = 120 V, I _E = 0		50	nA
	Collector Cut-Oir Current	V _{CB} = 120 V, I _E = 0, T _A = 100°C		50	μΑ
I _{EBO}	Emitter Cut-Off Current	$V_{EB} = 4.0 \text{ V}, I_{C} = 0$		50	nA
On Charac	cteristics				•
h _{FE} [$I_C = 1.0 \text{ mA}, V_{CE} = 5.0 \text{ V}$	80		
	DC Current Gain	I _C = 10 mA, V _{CE} = 5.0 V	80	250	
		I _C = 50 mA, V _{CE} = 5.0 V	30		
V _{CE(sat)}	Collector-Emitter Saturation Voltage	I _C = 10 mA, I _B = 1.0 mA		0.15	V
		I _C = 50 mA, I _B = 5.0 mA		0.20	V
V _{BE(sat)}	Base-Emitter On Voltage	I _C = 10 mA, I _B = 1.0 mA		1.0	V
		I _C = 50 mA, I _B = 5.0 mA		1.0	V
Small-Sigi	nal Characteristics				
f _T	Current Gain Bandwidth Product	$I_C = 10 \text{ mA}, V_{CE} = 10 \text{ V},$ f = 100 MHz	100		MHz
C _{obo}	Output Capacitance	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1.0 \text{ MHz}$		6.0	pF
C _{ibo}	Input Capacitance	$V_{BE} = 0.5 \text{ V}, I_{C} = 0, f = 1.0 \text{ MHz}$		20	pF
H _{fe}	Small-Signal Current Gain	$I_C = 1.0 \text{ mA}, V_{CE} = 10 \text{ V}, f = 1.0 \text{ kHz}$	50	250	
NF	Noise Figure	I_C = 250 μA, V_{CE} = 5.0 V, R_S =1.0 kΩ, f=10 Hz to 15.7 kHz		8.0	dB

Note:

4. PCB board size FR-4 76 x 114 x 0.6 T mm 3 (3.0 inch \times 4.5 inch \times 0.062 inch) with minimum land pattern size.

Typical Performance Characteristics

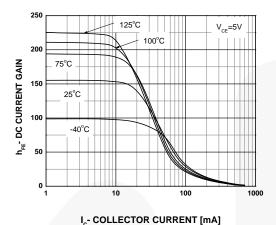


Figure 1. Typical Pulsed Current Gain vs. Collector Current

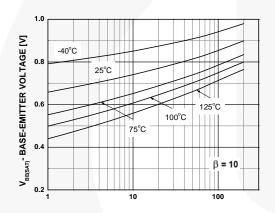


Figure 3. Base-Emitter Saturation Voltage vs. Collector Current

I_c- COLLECTOR CURRENT [mA]

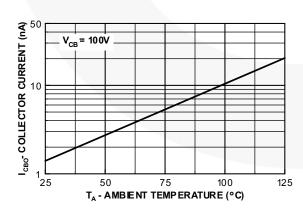
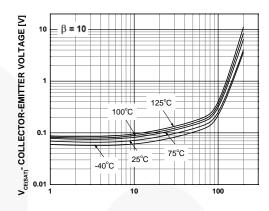
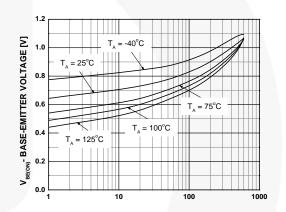


Figure 5. Collector Cut-Off Current vs. Ambient Temperature



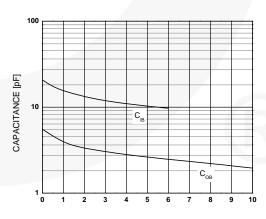
I - COLLECTOR CURRENT [mA]

Figure 2. Collector-Emitter Saturation Voltage vs. Collector Current



I_c- COLLECTOR CURRENT [mA]

Figure 4. Base-Emitter On Voltage vs. Collector Current



REVERSE BIAS VOLTAGE [V]

Figure 6. Input and Output Capacitance vs. Reverse Voltage

Typical Performance Characteristics (Continued)

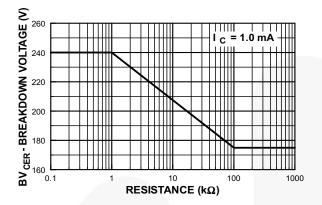


Figure 7. Collector- Emitter Breakdown Voltage with Resistance between Emitter-Base

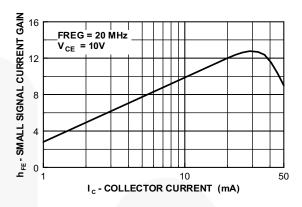


Figure 8. Small Signal Current Gain vs. Collector Current

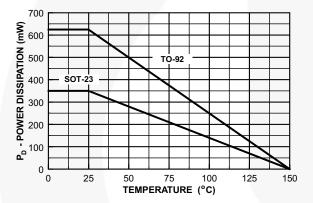


Figure 9. Power Dissipation vs. Ambient Temperature

Physical Dimensions

TO-92 (Bulk)

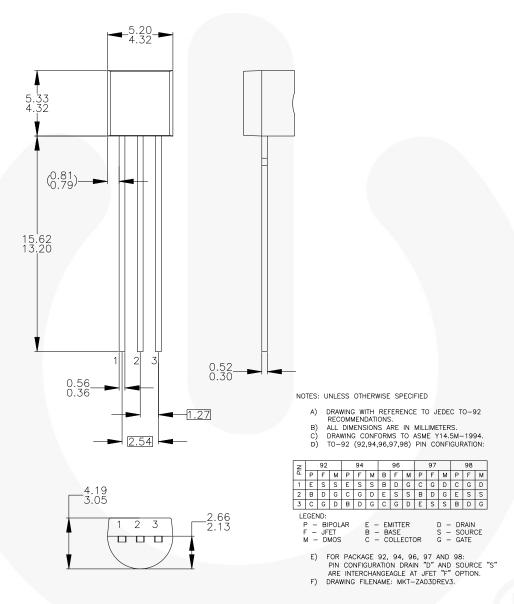


Figure 10. 3-LEAD, TO92, JEDEC TO-92 COMPLIANT STRAIGHT LEAD CONFIGURATION (OLD TO92AM3) (ACTIVE)

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Physical Dimensions (Continued)

TO-92 (Tape and Reel, Ammo)

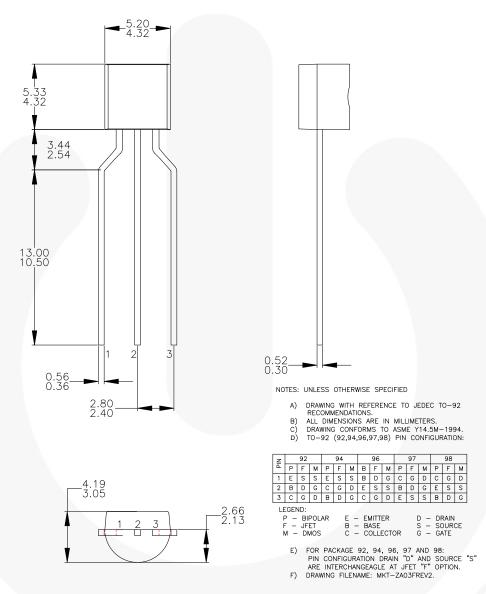


Figure 11. 3-LEAD, TO92, MOLDED, 0.200 IN-LINE SPACING LD FORM(J62Z OPTION) (ACTIVE)

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Physical Dimensions (Continued)

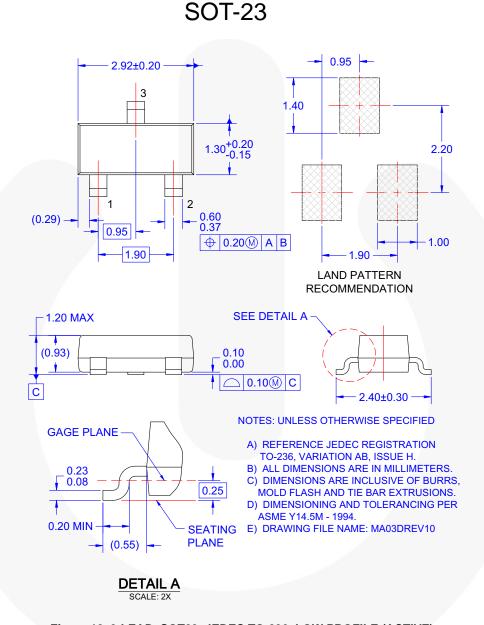


Figure 12. 3-LEAD, SOT23, JEDEC TO-236, LOW PROFILE (ACTIVE)

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